

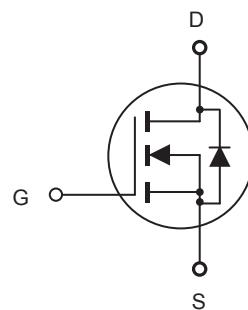


# CED4204/CEU4204

## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 40V, 24A,  $R_{DS(ON)} = 28m\Omega$  @ $V_{GS} = 10V$ .  
 $R_{DS(ON)} = 42m\Omega$  @ $V_{GS} = 4.5V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Lead free product is acquired.
- TO-251 & TO-252 package.



### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	24	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	96	A
Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above $25^\circ C$	$P_D$	29 0.23	W W/ $^\circ C$
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{JC}$	4.3	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	$R_{JA}$	50	$^\circ C/W$



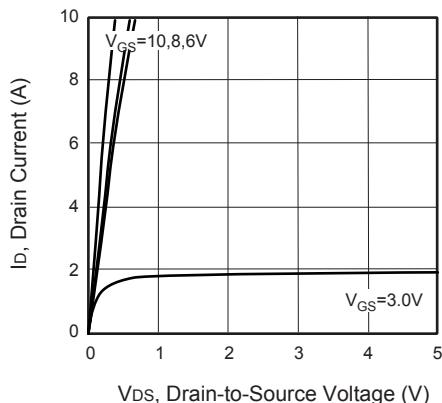
# CED4204/CEU4204

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

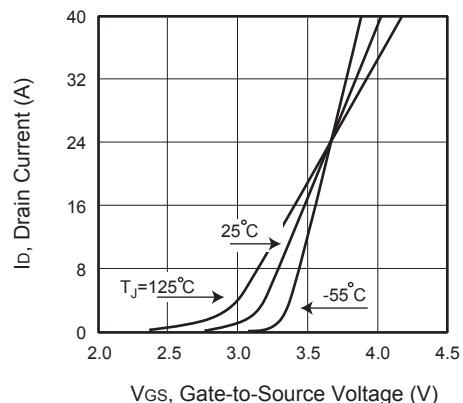
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 6\text{A}$		22	28	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 5\text{A}$		30	42	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		590		pF
Output Capacitance	$C_{\text{oss}}$			90		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			60		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 20\text{V}, I_D = 6\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 3\Omega$		10	20	ns
Turn-On Rise Time	$t_r$			3	6	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			26	52	ns
Turn-Off Fall Time	$t_f$			4	8	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 20\text{V}, I_D = 6\text{A}, V_{\text{GS}} = 10\text{V}$		13	16.9	nC
Gate-Source Charge	$Q_{\text{gs}}$			1.7		nC
Gate-Drain Charge	$Q_{\text{gd}}$			3.5		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$				24	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 1\text{A}$			1.2	V

Notes :

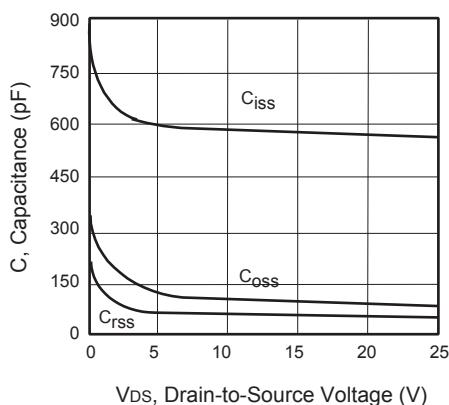
- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- c.Guaranteed by design, not subject to production testing.



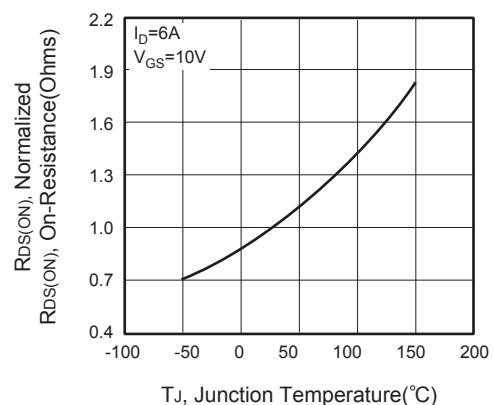
**Figure 1. Output Characteristics**



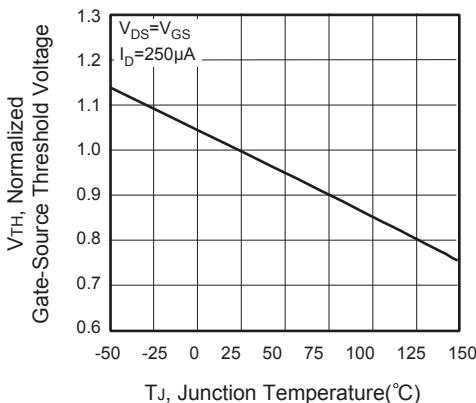
**Figure 2. Transfer Characteristics**



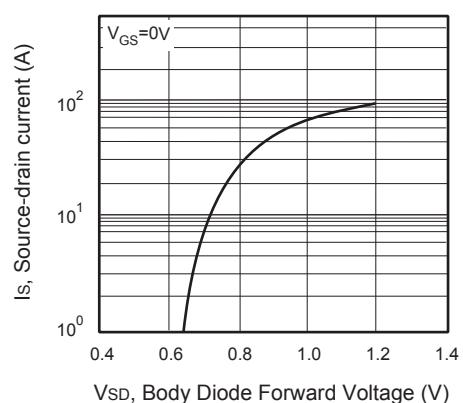
**Figure 3. Capacitance**



**Figure 4. On-Resistance Variation with Temperature**



**Figure 5. Gate Threshold Variation with Temperature**



**Figure 6. Body Diode Forward Voltage Variation with Source Current**

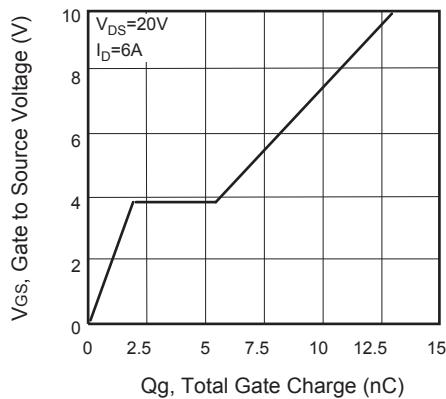


Figure 7. Gate Charge

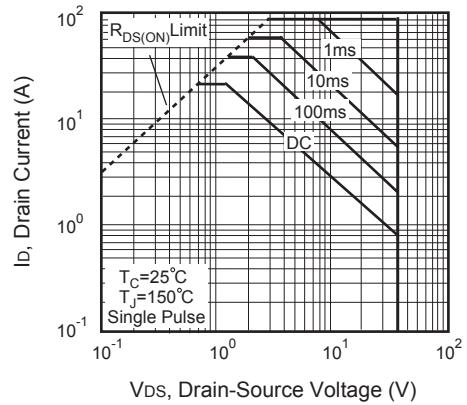


Figure 8. Maximum Safe Operating Area

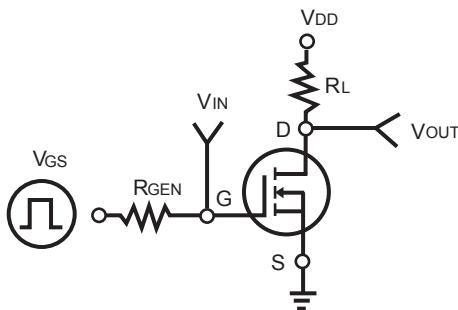


Figure 9. Switching Test Circuit

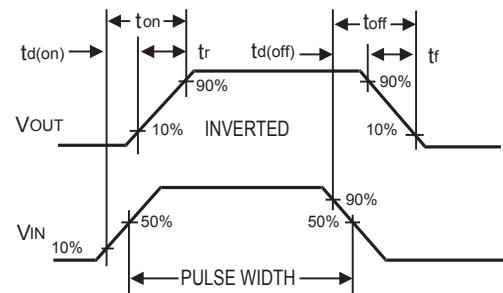


Figure 10. Switching Waveforms

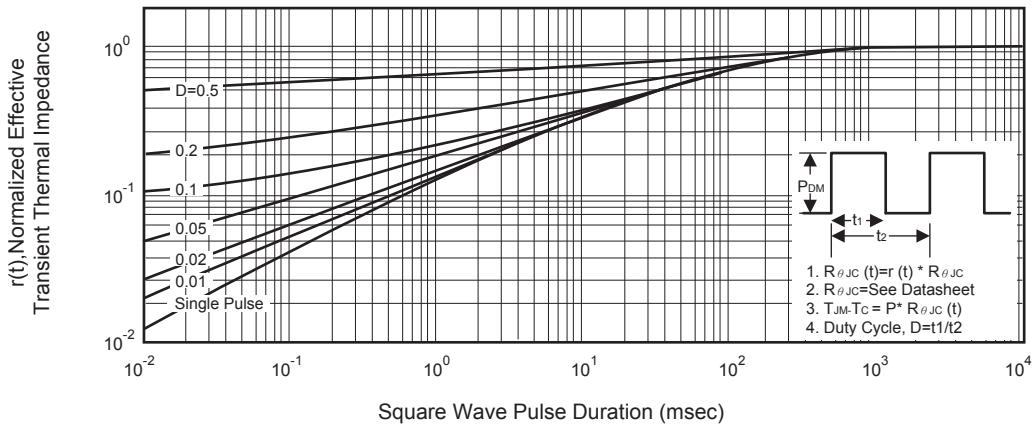


Figure 11. Normalized Thermal Transient Impedance Curve